The DRC brings together scientists, engineers, and students to present breakthroughs and advances in device research. DRC is sponsored by the IEEE, Electron Devices Society. The conference will be held at the University of Notre Dame, Notre Dame, Indiana from Monday, June 21 through Wednesday, June 23, 2004.

The DRC will be coordinated with the EMC (Electronic Materials Conference) during the same week, June 23-25, 2004, at the University of Notre Dame. The coordinated efforts are made in recognition of the strong interaction between device and electronic materials research and provides for fruitful exchange of information between attendees of both conferences. For further information about the EMC, see www.tms.org/Meetings/Specialty/EMC04/EMC04.html.

PLENARY AND INVITED SPEAKERS

Plenary and invited speakers will present the latest developments in emerging device technologies including scaled silicon, wide bandgaps, carbon nanotubes, molecular electronics, large-area electronics, bio-inspired electronics, and spintronics.

Partial List of Invited Speakers:
Yasuhiko Arakawa (University of Tokyo)
Sanjay Banerjee (University of Texas, Austin)
David Emerson (CREE, Inc.)
Stephen Empeodoce (Nanosys, Inc.)
Mark Hershman (Northwestern University)
Thomas Jackson (Penn State University)
Thomas Knight (Massachusetts Institute of Technology)
Mark Lundstrom (Purdue University)
Richard Martel (University of Montreal)
Umesh Mishra (University of California, Santa Barbara)
Hiroo Munekata (Tokyo Institute of Technology)
Nongjian Tao (Arizona State University)
Lucas Worschech (University of Wurzburg)

PAPERS ARE SOLICITED ON HIGH PERFORMANCE AND NOVEL DEVICES INCLUDING, BUT NOT LIMITED TO THE FOLLOWING:

- Amorphous & polycrystalline devices
- Carbon nanotube devices
- Devices for displays & imaging
- Device modeling
- III-V FET and bipolar transistors
- Integrated optoelectronics
- High voltage/high power devices
- Magnetic devices
- Micro/nanoelectromechanical devices
- Millimeter wave and ultrafast devices
- Molecular devices
- Nanofabrication technology for devices
- Nonvolatile, static and dynamic memory
- Optical sources and detectors
- Organic emitters and transistors
- Plastic electronics
- Quantum-effect and single-electron devices
- Reliability
- Sensors
- SiGe, SiGeC, and SiC devices
- Silicon CMOS/BiCMOS
- Silicon scaled and nanoscale devices
- SOI and 3-D Devices
- Spin-based devices
- Superconducting devices
- Thin film transistors
- Tunneling and hot-electron devices
- Wide-bandgap devices

TECHNICAL PROGRAM COMMITTEE
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Yifeng Wu, CREE Santa Barbara Technology Center
John Zolper, DARPA/MTO

POSTER AND RUMP SESSIONS
Building on the success of poster sessions in previous years, abstracts will again be accepted for poster presentations at DRC 2004. In the DRC tradition, rump sessions will continue to provide a forum for frank discussion of contentious topics in device research and applications.

BEST STUDENT PAPER AWARD
Papers presented by students, based on their own research, are eligible for this annual award. The abstract must be identified as a “Student Paper” during the submission process to be eligible for this award.

CALL FOR PAPERS
Authors are requested to see the DRC website, www.tms.org/Meetings/Specialty/DRC/2004/DRC-2004-Home.html for paper submission instructions, or contact Alan Seabaugh, Technical Program Chair. Abstracts sent by facsimile will not be accepted.

Abstracts submitted to DRC may not be submitted to EMC.

ABSTRACT DEADLINE: March 2, 2004

FURTHER INFORMATION
Note: Registration and Housing information will be available in April 2004.

Early registration is encouraged with a reduced registration fee offered as an incentive. Students will also receive a reduced registration fee. Limited travel funds are available to students presenting papers. Further information on student assistance may be obtained by writing to Pallab Bhattacharya, General Program Chair.

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All prospective authors/attendees, please complete and return

☐ I plan to attend the conference.
☐ I wish to make a presentation at the conference and have enclosed an abstract.
☐ Please send me future announcements.

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